Data Sheet

PS2561D-1, PS2561DL-1, PS2561DL1-1, PS2561DL2-1

DIP PHOTOCOUPLER OPERATING AMBIENT TEMPERATURE 110 °C

DESCRIPTION

RENESAS

The PS2561D-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2561D-1 is in a plastic DIP (Dual In-line Package) and the PS2561DL-1 is lead bending type (Gullwing) for surface mount.

: PS2561DL2-1-F3 : 2 000 pcs/reel

RENESAS

The PS2561DL1-1 is lead bending type for long creepage distance.

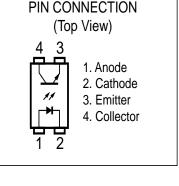
The PS2561DL2-1 is lead bending type for long creepage distance (Gull-wing) for surface mount.

FEATURES

- Operating ambient temperature: 110 °C
- High isolation voltage (BV = 5 000 Vr.m.s.)
- High collector to emitter voltage (V_{CEO} = 80 V)
- High current transfer ratio (CTR = 160 % TYP.)
- High-speed switching ($t_r = 3 \ \mu s \ TYP$., $t_f = 5 \ \mu s \ TYP$.)
- Ordering number of taping product: PS2561DL-1-F3 : 2 000 pcs/reel
- •
- Pb-Free product
- Safety standards
 - UL approved: UL1577, Double protection
 - CSA approved: CAN/CSA-C22.2 No. 62368-1, Reinforced insulation
 - BSI approved: BS EN 62368-1, Reinforced insulation
 - SEMKO approved: EN 62368-1, IEC 62368-1, Reinforced insulation
 - NEMKO approved: EN 62368-1, Reinforced insulation
 - FIMKO approved: EN 62368-1, Reinforced insulation
 - DEMKO approved: EN 62368-1, Reinforced insulation
 - CQC approved: GB8898, GB4943.1, Reinforced insulation
 - VDE approved: DIN EN 60747-5-5 (Option)

APPLICATIONS

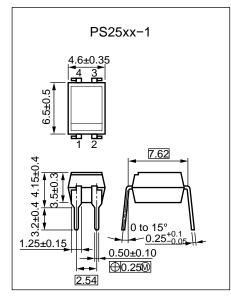
- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controllers



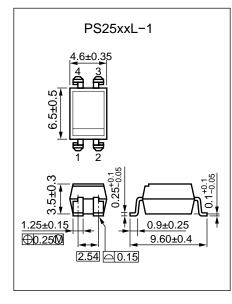
R08DS0181EJ0101 Rev.1.01 Feb 21, 2022

PACKAGE DIMENSIONS (UNIT: mm)





Lead Bending Type

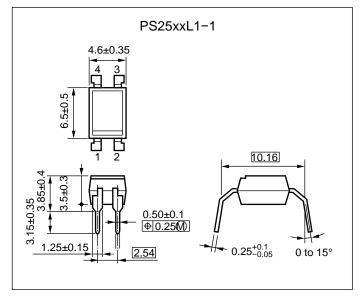


Weight (4-pin DIP) : 0.26 g (typ.)

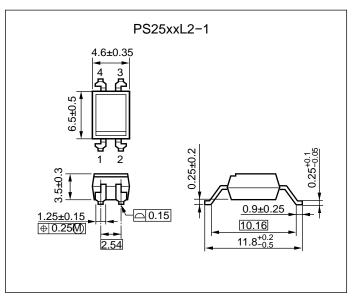
PHOTOCOUPLER CONSTRUCTION

| Parameter | PS2561D-1, PS2561DL-1 | PS2561DL1-1, PS2561DL2-1 |
|---------------------------|-----------------------|--------------------------|
| Air Distance (MIN.) | 7 mm | 8 mm |
| Creepage Distance (MIN.) | 7 mm | 8 mm |
| Isolation Distance (MIN.) | 0.4 mm | 0.4 mm |

Long Creepage Distance

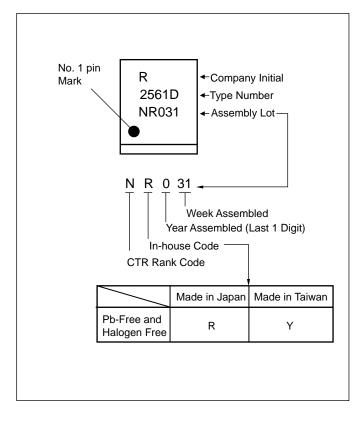


Long Creepage Distance (Gull-Wing)





MARKING EXAMPLE



ORDERING INFORMATION

| Part Number | Order Number *1 | Solder Plating Specification | Packing Style | Safety Standard Approval | Application Part Number *2 | |
|------------------|---------------------|---------------------------------|---------------------------------|--------------------------------|---------------------------------|----------|
| PS2561D-1 | PS2561D-1Y-A | Pb-Free and | Magazine case 100 pcs | Standard products | PS2561D-1 | |
| PS2561DL-1 | PS2561DL-1Y-A | Halogen Free | | (UL, CSA, BSI, | PS2561DL-1 | |
| PS2561DL1-1 | PS2561DL1-1Y-A | | | SEMKO, NEMKO, FIMKO, DEMKO, | PS2561DL1-1 | |
| PS2561DL2-1 | PS2561DL2-1Y-A | | | CQC approved) | PS2561DL2-1 | |
| PS2561DL-1-F3 | PS2561DL-1Y-F3-A | | Embossed Tape 2 000 pcs/reel | | PS2561DL-1 | |
| PS2561DL2-1-F3 | PS2561DL2-1Y-F3-A | | Embossed Tape 2 000 pcs/reel | | PS2561DL2-1 | |
| PS2561D-1-V | PS2561D-1Y-V-A | | Magazine case 100 pcs | UL, CSA, BSI, | PS2561D-1 | |
| PS2561DL-1-V | PS2561DL-1Y-V-A | | | SEMKO, NEMKO, | PS2561DL-1 | |
| PS2561DL1-1-V | PS2561DL1-1Y-V-A | | | FIMKO, DEMKO, CQC, | PS2561DL1-1 | |
| PS2561DL2-1-V | PS2561DL2-1Y-V-A | | | DIN EN 60747-5-5 | PS2561DL2-1 | |
| PS2561DL-1-V-F3 | PS2561DL-1Y-V-F3-A | | | | Embossed Tape 2 000 pcs/reel | approved |
| PS2561DL2-1-V-F3 | PS2561DL2-1Y-V-F3-A | | Embossed Tape 2 000 pcs/reel | | PS2561DL2-1 | |

Notes: *1. If requested by Order Number in the table, all CTR rank (CTR = 50-400 % (@ $I_F = 5 \text{ mA}$, $V_{CE} = 5 \text{ V}$) & CTR = 10 % and larger (@ $I_F = 1 \text{ mA}$, $V_{CE} = 5 \text{ V}$)) products will be shipped.

When specifying CTR rank, please add "/CTR rank" after Order Number.

ex. L rank : PS2561D-1Y-A/L

Notes: *2. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

| Parameter | | Symbol | Ratings | Unit |
|----------------------------|-------------------------------|---------------------|-------------|---------|
| Diode | Reverse Voltage | VR | 6 | V |
| | Forward Current (DC) | lF | 40 | mA |
| | Power Dissipation Derating | ∆P _D /°C | 1.5 | mW/°C |
| | Power Dissipation | PD | 150 | mW |
| | Peak Forward Current*1 | IFP | 1 | А |
| Transistor | Collector to Emitter Voltage | VCEO | 80 | V |
| | Emitter to Collector Voltage | V _{ECO} | 7 | V |
| | Collector Current | | 50 | mA |
| Power Dissipation Derating | | ∆Pc/°C | 1.5 | mW/°C |
| Power Dissipation | | Pc | 150 | mW |
| Isolation Voltage*2 | | BV | 5 000 | Vr.m.s. |
| Operating | Operating Ambient Temperature | | -55 to +110 | °C |
| Storage Temperature | | T _{stg} | -55 to +150 | °C |

Note: *1. PW = 100 μ s, Duty Cycle = 1 %

*2. AC voltage for 1 minute at $T_A = 25$ °C, RH = 60 % between input and output. Pins 1-2 shorted together, 3-4 shorted together.



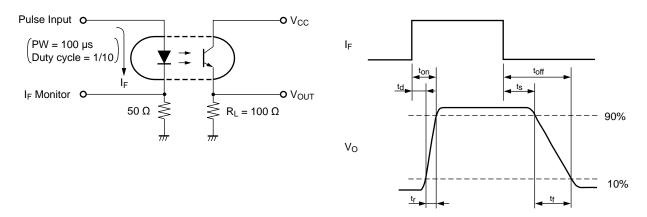
| | Parameter | Symbol | Conditions | MIN. | TYP. | MAX. | Unit |
|------------|--------------------------------------|-----------|------------------------|------------------|------|------|------|
| Diode | Forward Voltage | VF | IF = 10 mA | | 1.2 | 1.4 | V |
| | Reverse Current | lr | Vr = 5 V | | | 5 | μA |
| | Terminal Capacitance | Ct | V = 0 V, f = 1.0 MHz | | 10 | | pF |
| Transistor | Collector to Emitter Dark Current | Iceo | Vce = 48 V, IF = 0 mA | | | 100 | nA |
| Coupled | Current Transfer Ratio | CTR | IF = 5 mA, Vce = 5 V | 50 | 160 | 400 | % |
| | (Ic/IF)*1 | | IF = 1 mA, VCE = 5 V | 10 | 80 | | |
| | Collector Saturation Voltage | VCE (sat) | IF = 10 mA, Ic = 2 mA | | | 0.3 | V |
| | Isolation Resistance | Rı-o | VI-0 = 1.0 kVDC | 10 ¹¹ | | | Ω |
| | Isolation Capacitance | Сі-о | V = 0 V, f = 1.0 MHz | | 0.5 | | pF |
| | Rise Time*2 | tr | Vcc = 10 V, Ic = 2 mA, | | 3 | | μs |
| | Fall Time ^{*2} | tr | RL = 100 Ω | | 5 | | |

ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

Note: *1. CTR rank

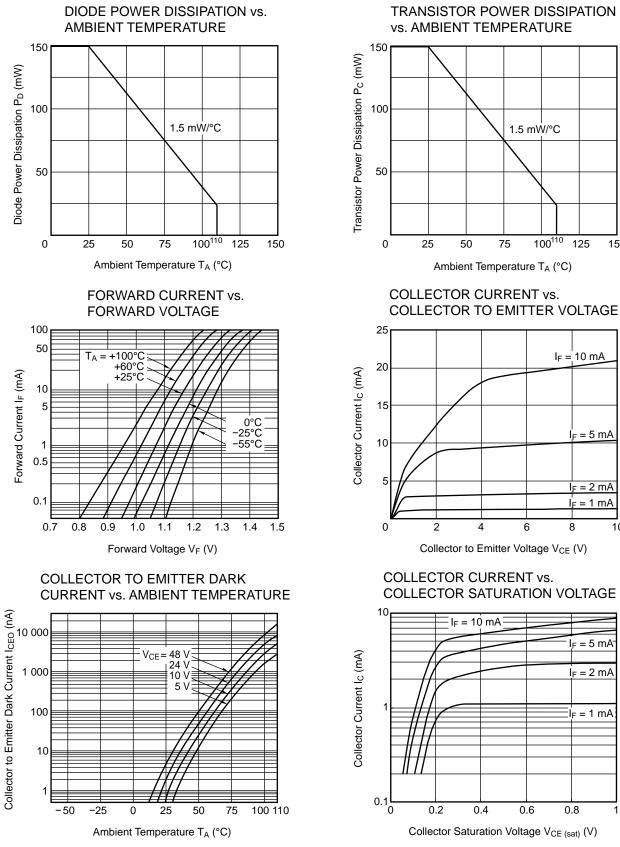
| CTR Rank | CTR (%) | Conditions |
|----------|---------------|----------------------|
| | 80 to 160 | IF = 5 mA, VCE = 5 V |
| Н | 16 and larger | IF = 1 mA, Vce = 5 V |
| | 100 to 200 | IF = 5 mA, Vce = 5 V |
| Q | 20 and larger | IF = 1 mA, Vce = 5 V |
| W | 130 to 260 | IF = 5 mA, VCE = 5 V |
| | 26 and larger | IF = 1 mA, Vce = 5 V |
| | 200 to 400 | IF = 5 mA, VCE = 5 V |
| | 40 and larger | IF = 1 mA, Vce = 5 V |
| Ν | 50 to 400 | IF = 5 mA, Vce = 5 V |
| | 10 and larger | IF = 1 mA, Vce = 5 V |

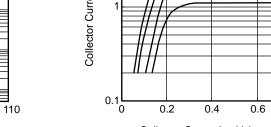
*2. Test Circuit for Switching Time





TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)





Collector Saturation Voltage V_{CE (sat)} (V)

1.5 mW/°C

100¹¹⁰

125

 $I_{F} = 10 \text{ mA}$

l_F = 5 mA

 $I_F = 2 \text{ mA}$

 $I_F = 1 \text{ mA}$

= = 5 mA

. I_F = 2 mA

F = 1 mA

0.8

10

8

150

75

Ambient Temperature T_A (°C)

50

25

2

4

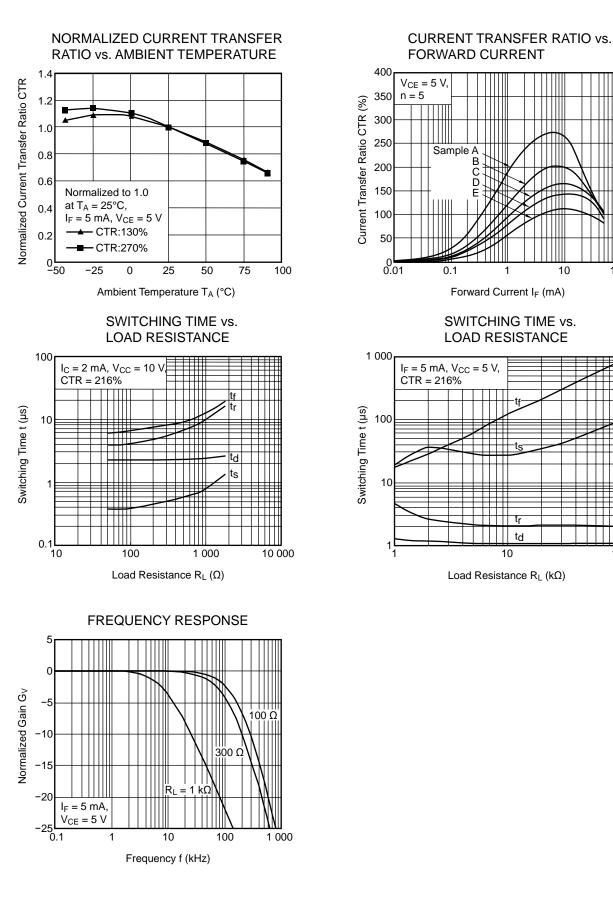
 $I_F = 10 \text{ mA}$

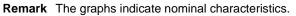
6

Collector to Emitter Voltage V_{CE} (V)

Remark The graphs indicate nominal characteristics.

1.0







10

100

100

D

Forward Current I_F (mA)

SWITCHING TIME vs.

tr

td

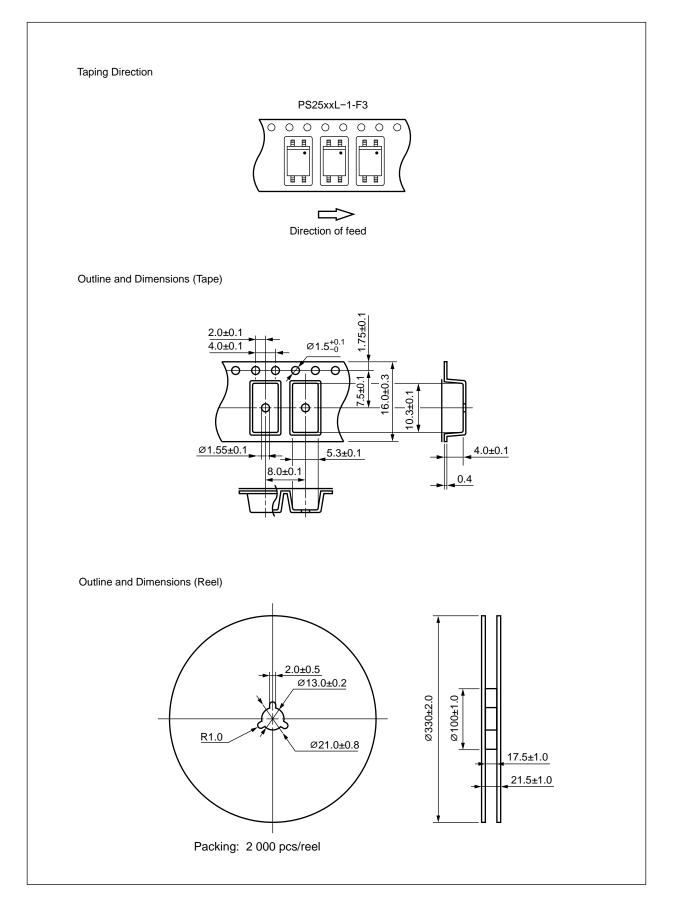
10

Load Resistance R_L (kΩ)

LOAD RESISTANCE

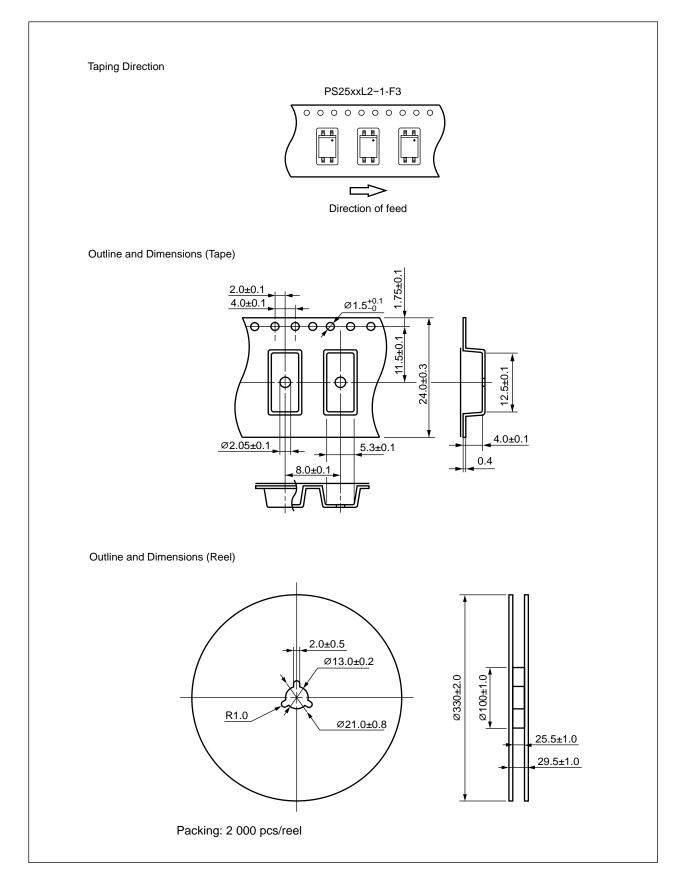
0.1

TAPING SPECIFICATIONS (UNIT: mm)

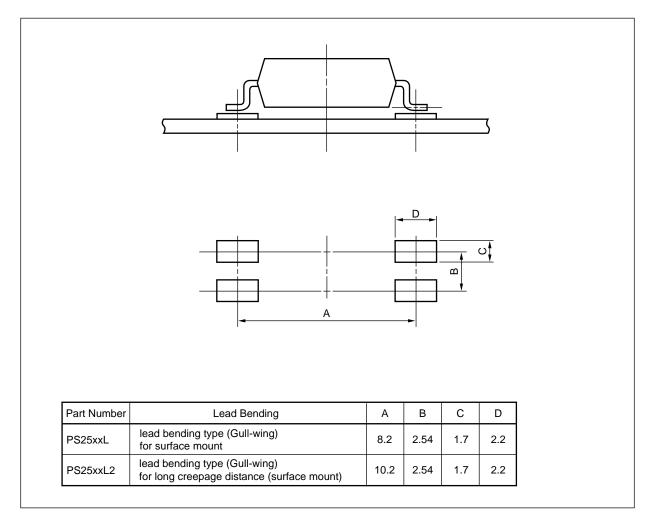




TAPING SPECIFICATIONS (UNIT: mm)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark All dimensions in this figure must be evaluated before use.



NOTES ON HANDLING

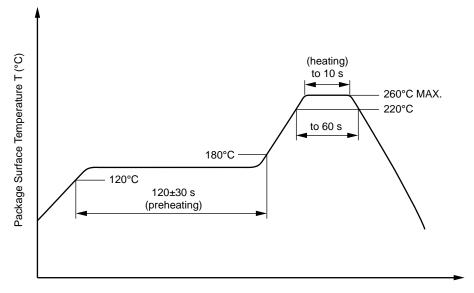
- 1. Recommended soldering conditions
 - (1) Infrared reflow soldering
 - Peak reflow temperature
 - Time of peak reflow temperature
 - Time of temperature higher than 220 °C
 - Time to preheat temperature from 120 to 180 °C 120 ± 30 s
 - Number of reflows
 - Flux

10 seconds or less 60 seconds or less Three Rosin flux containing small amount of chlorine

260 °C or below (package surface temperature)

(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

- (2) Wave soldering
 - Temperature

• Time

- 10 seconds or less • Preheating conditions 120 °C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)

260 °C or below (molten solder temperature)

Rosin flux containing small amount of chlorine (The flux with a maximum • Flux chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

• Peak Temperature (lead part temperature) 350 °C or below

3 seconds or less

 Time (each pins) • Flux

- Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)
- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead
- (b) Please be sure that the temperature of the package would not be heated over 100 °C
- (4) Cautions
 - Flux Cleaning

Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.

• Do not use fixing agents or coatings containing halogen-based substances.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

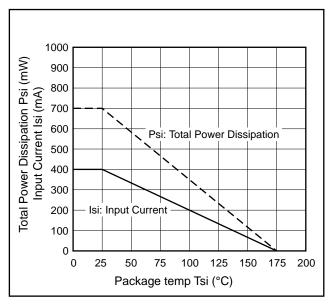
- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.
- 3. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- 4. Do not use fixing agents or coatings containing halogen-based substances.



SPECIFICATION OF VDE MARKS LICENSE DOCUMENT (1/2) (PS2561D-1, PS2561DL-1)

| Parameter | Symbol | Rating | Unit |
|---|--------------------------------------|--------------------------------------|--|
| Climatic test class (IEC 60068-1/DIN EN 60068-1) | | 55/110/21 | |
| Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.6 \times U_{IORM}, P_d < 5 \text{ pC}$ | U _{IORM} U _{pr} | 890 1 424 | V _{peak} V _{peak} |
| Test voltage (partial discharge test, procedure b for all devices) U_{pr} = 1.875 \times $U_{IORM},~P_d < 5~pC$ | Upr | 1 669 | V_{peak} |
| Highest permissible overvoltage | UIOTM | 8 000 | V _{peak} |
| Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1) | | 2 | |
| Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11)) | СТІ | 175 | |
| Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1)) | | lll a | |
| Storage temperature range | T _{stg} | -55 to +150 | °C |
| Operating temperature range | T _A | -55 to +110 | °C |
| Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc at } T_A = 25 \text{ °C}$ $V_{IO} = 500 \text{ V dc at } T_A \text{ MAX. at least } 100 \text{ °C}$ | Ris MIN. Ris MIN. | 10 ¹² 10 ¹¹ | Ω Ω |
| Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I_F , Psi = 0) Power (output or total power dissipation) | Tsi Isi Psi | 175 400 700 | °C mA mW |
| Isolation resistance $V_{IO} = 500 \text{ V} \text{ dc} \text{ at } T_A = T \text{si}$ | Ris MIN. | 10 ⁹ | Ω |

Dependence of maximum safety ratings with package temperature

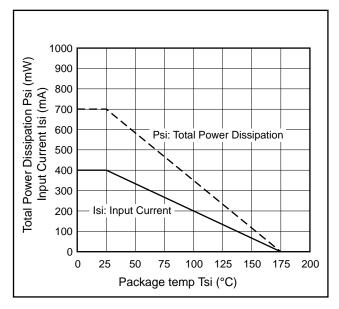




SPECIFICATION OF VDE MARKS LICENSE DOCUMENT (2/2) (PS2561DL1-1, PS2561DL2-1)

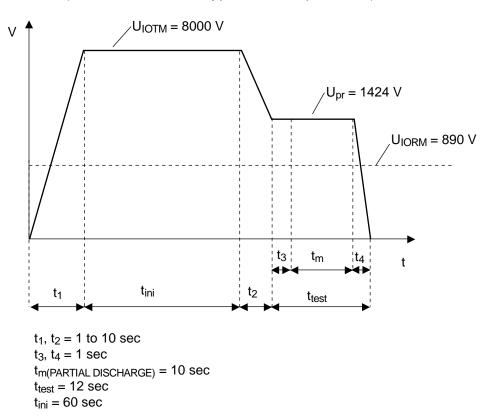
| Parameter | Symbol | Rating | Unit |
|--|--------------------------------------|--------------------------------------|--|
| Climatic test class (IEC 60068-1/DIN EN 60068-1) | | 55/110/21 | |
| Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.6 \times U_{IORM}, P_d < 5 \text{ pC}$ | U _{IORM} U _{pr} | 1 130 1 808 | V _{peak} V _{peak} |
| Test voltage (partial discharge test, procedure b for all devices) U_{pr} = 1.875 \times $U_{IORM},~P_d < 5~pC$ | Upr | 2 119 | V _{peak} |
| Highest permissible overvoltage | UIOTM | 8 000 | V_{peak} |
| Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1) | | 2 | |
| Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11)) | CTI | 175 | |
| Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1)) | | lll a | |
| Storage temperature range | T _{stg} | -55 to +150 | °C |
| Operating temperature range | T _A | -55 to +110 | °C |
| Isolation resistance, minimum value $V_{IO} = 500 \text{ V} \text{ dc} \text{ at } T_A = 25 ^{\circ}\text{C}$ $V_{IO} = 500 \text{ V} \text{ dc} \text{ at } T_A \text{ MAX. at least } 100 ^{\circ}\text{C}$ | Ris MIN. Ris MIN. | 10 ¹² 10 ¹¹ | Ω Ω |
| Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I _F , Psi = 0) Power (output or total power dissipation) | Tsi Isi Psi | 175 400 700 | °C mA mW |
| Isolation resistance $V_{10} = 500 \text{ V dc at } T_A = Tsi$ | Ris MIN. | 10 ⁹ | Ω |

Dependence of maximum safety ratings with package temperature

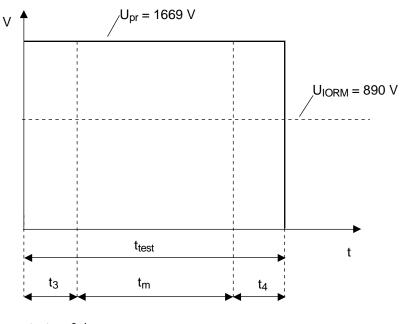




Method a) Destructive Test, Type and Sample Test (PS2561D-1, PS2561DL-1)

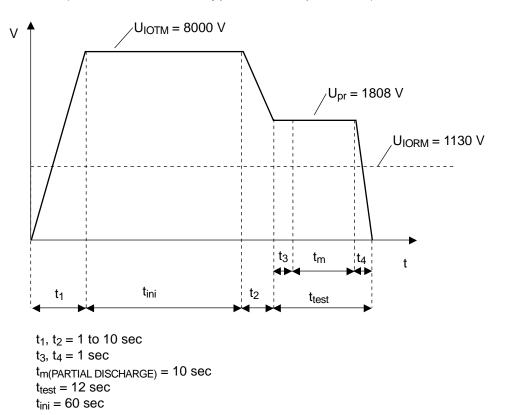


Method b) Non-destructive Test, 100 % Production Test (PS2561D-1, PS2561DL-1)

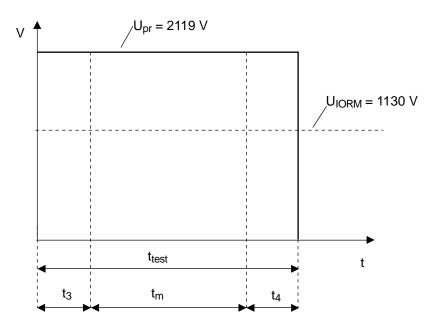


 $t_3, \, t_4 = 0.1 \; \text{sec} \\ t_m(\text{PARTIAL DISCHARGE}) = 1.0 \; \text{sec} \\ t_{test} = 1.2 \; \text{sec} \\$

Method a) Destructive Test, Type and Sample Test (PS2561DL1-1, PS2561DL2-1)



Method b) Non-destructive Test, 100% Production Test (PS2561DL1-1, PS2561DL2-1)



 $t_{3}, \, t_{4} = 0.1 \; \text{sec} \\ t_{m}(\text{PARTIAL DISCHARGE}) = 1.0 \; \text{sec} \\ t_{test} = 1.2 \; \text{sec} \\ }$

| Caution GaAs Products | This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. |
|-----------------------|--|
| | • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. |
| | Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. |
| | Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. |
| | • Do not burn, destroy, cut, crush, or chemically dissolve the product. |
| | • Do not lick the product or i any way allow it to enter the mouth. |

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